

Final Product Change Notification

Issue Date: 09-Aug-2017 Effective Date: 06-Nov-2017

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Change Category

[] Wafer Fab Process [] Assembly [] Product Marking [] Test [] Design Process Location [] Wafer Fab Materials [] Mechanical []Test [X] [] Errata Assembly Specification **Process** Materials [] Assembly [] [] Wafer Fab Location [] Test [] Electrical Packing/Shipping/Labeling Equipment spec./Test Location coverage

i.MX 6UltraLite Molding Compound Change From G770FL to G770SFL

Details of this Change

NXP Semiconductors is announcing the successful qualification of molding compound change from G770FL to G770SFL (low alpha) for i.MX 6UltraLite 14x14 BGA and 9x9 BGA parts. G770SFL (low alpha) had better performance than G770FL on SER failure rate.

Corresponding ZVEI Delta Qualification Matrix ID: SEM-PA-11

Why do we Implement this Change

Molding compound change from G770FL to G770SFL (low alpha) will improve SER performance. Molding compound G770FL and G770SFL (low alpha) have same composition. G770SFL (low alpha) molding compound has better control on alpha particle than G770FL.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Samples are available from 07-Aug-2017

The available sample part number is PCIMX6G2CVM05AB.

Production

Planned first shipment 30-Nov-2017

Impact

There is no change to product form, fit, function, or reliability.

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 08-Sep-2017.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Xuyang Wang Position Product Engineer

e-mail address xuyang.wang@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

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Changed Orderable Part#	Changed Part 12NC	Changed Part Number	Changed Part Description	Package Name	Status	Product Line
MCIMX6G2CVK05AA	935322295557	MCIMX6G2CVK05AA	i.MX6UL 9X9	LFBGA272	DOD	BL Microcontrollers
MCIMX6G3DVM05AA	935316313557	MCIMX6G3DVM05AA	i.MX6UL	LFBGA289	DOD	BL Microcontrollers
MCIMX6G2AVM05AA	935313145557	MCIMX6G2AVM05AA	i.MX6UL	LFBGA289	DOD	BL Microcontrollers
MCIMX6G2DVK05AA	935324976557	MCIMX6G2DVK05AA	i.MX6UL 9x9	LFBGA272	DOD	BL Microcontrollers
MCIMX6G2DVM05AA	935318783557	MCIMX6G2DVM05AA	i.MX6UL	LFBGA289	DOD	BL Microcontrollers
MCIMX6G3DVK05AA	935323757557	MCIMX6G3DVK05AA	i.MX6UL 9x9	LFBGA272	DOD	BL Microcontrollers
MCIMX6G2AVM07AA	935313166557	MCIMX6G2AVM07AA	i.MX6UL Auto	LFBGA289	DOD	BL Microcontrollers